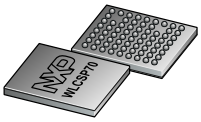

SOT2146-1

WLCSP70, wafer level chip scale package, 70 terminals, 0.35 mm pitch, 3.64 mm x 3.16 mm x 0.49 mm body (backside coating included)

1 December 2021 **Package information**

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP70
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	01-06-2021
Manufacturer package code	98ASA01767D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	3.61	3.64	3.67	mm
package width	3.13	3.16	3.19	mm
package height	-	0.49	0.525	mm
nominal pitch	-	0.35	-	mm
actual quantity of termination	-	70	-	

WLCSP70, wafer level chip scale package, 70 terminals, 0.35 mm pitch, 3.64 mm x 3.16 mm x 0.49 mm body (backside coating included)

2 Package outline

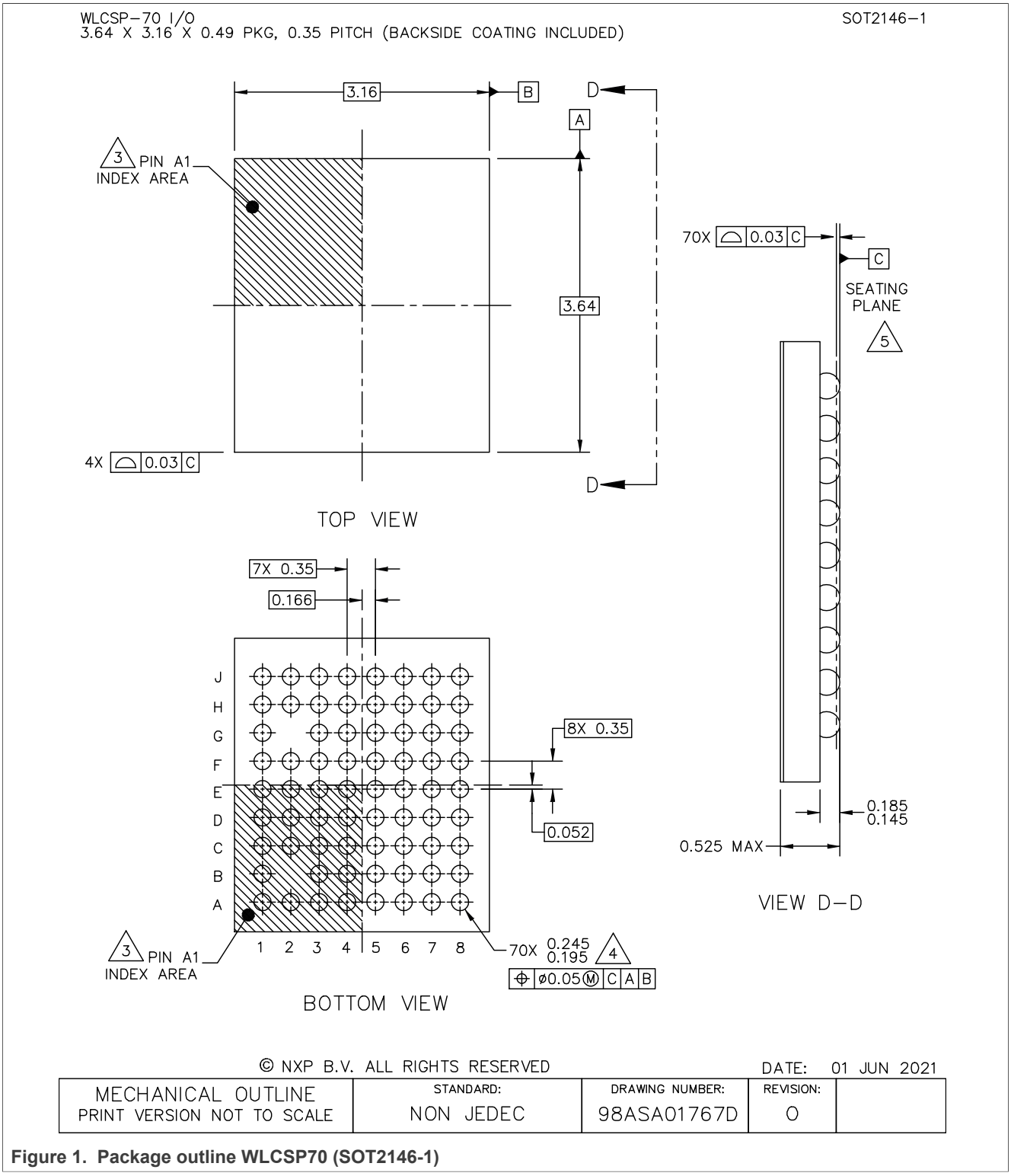

Figure 1. Package outline WLCSP70 (SOT2146-1)

3 Soldering

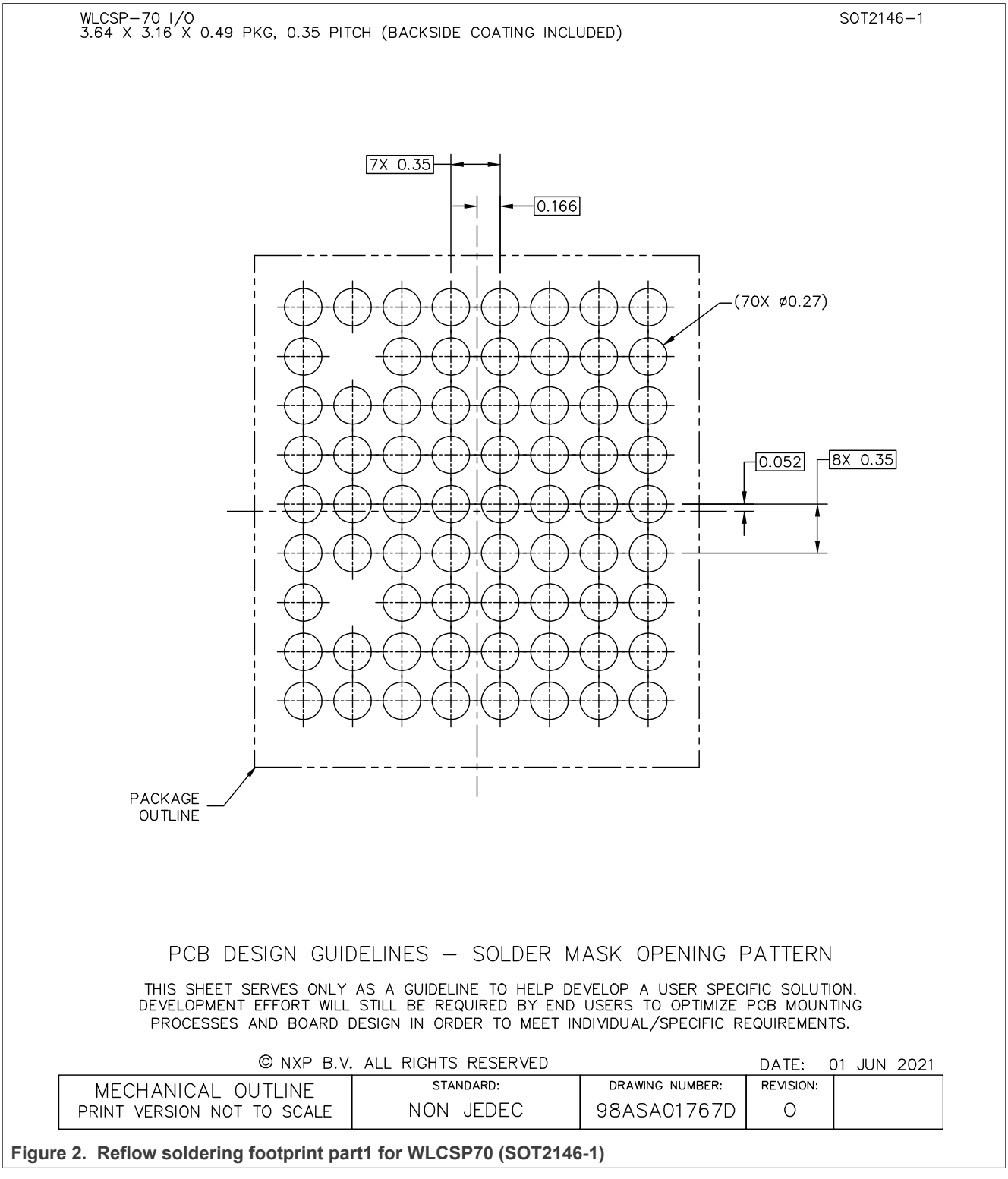

Figure 2. Reflow soldering footprint part1 for WLCSP70 (SOT2146-1)

WLCSP70, wafer level chip scale package, 70 terminals, 0.35 mm pitch, 3.64 mm x 3.16 mm x 0.49 mm body (backside coating included)

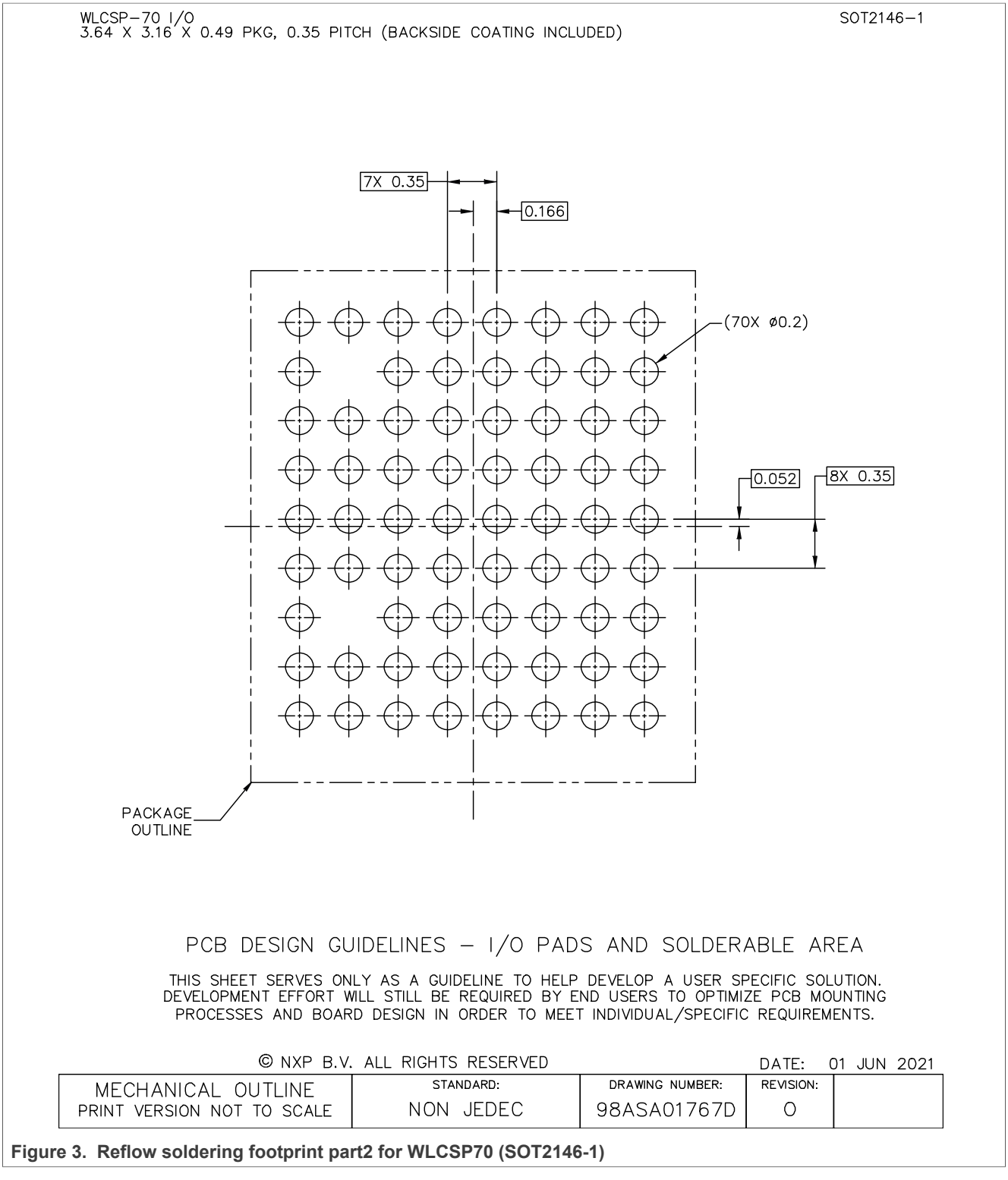

Figure 3. Reflow soldering footprint part2 for WLCSP70 (SOT2146-1)

WLCSP70, wafer level chip scale package, 70 terminals, 0.35 mm pitch, 3.64 mm x 3.16 mm x 0.49 mm body (backside coating included)

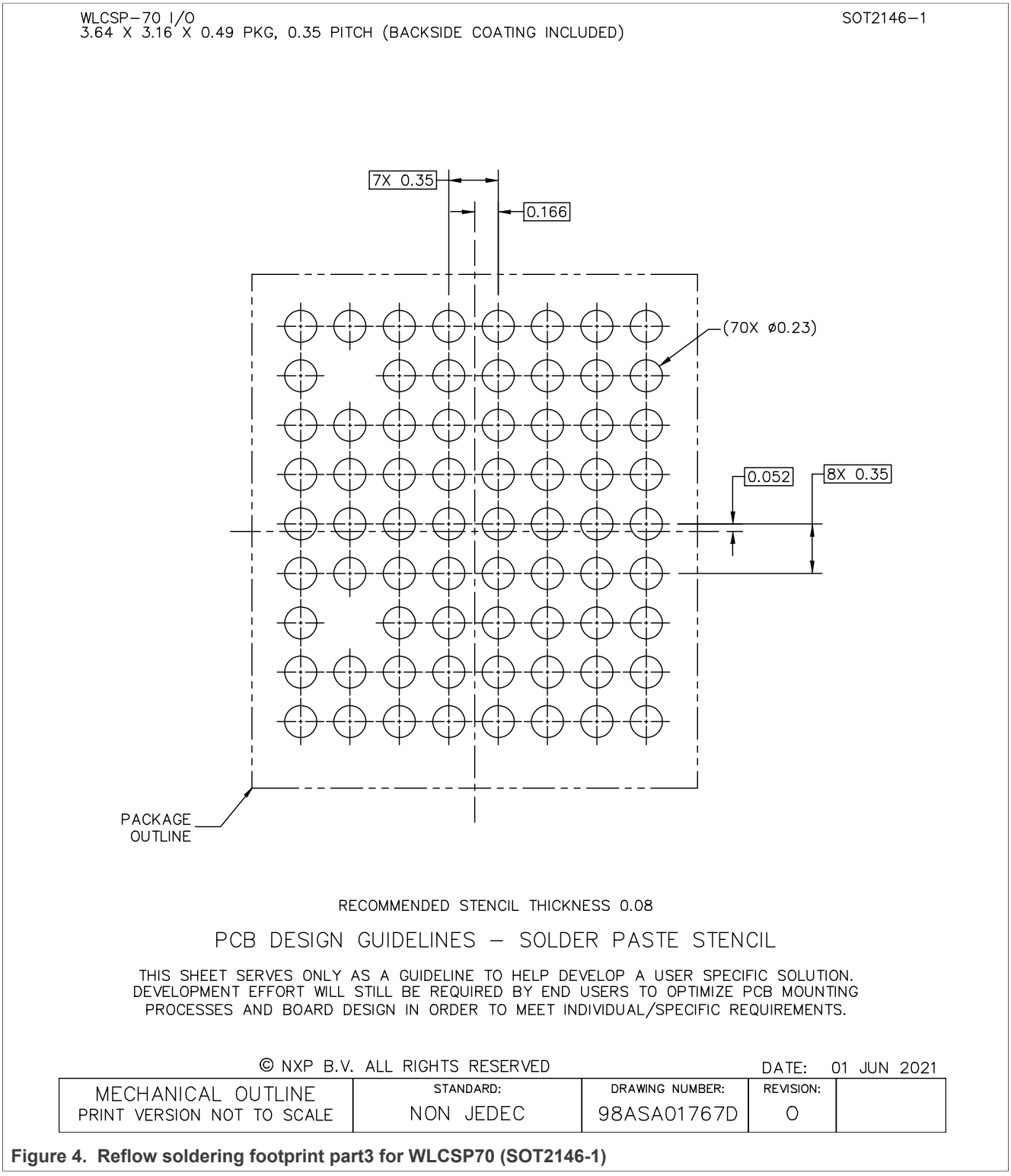

Figure 4. Reflow soldering footprint part3 for WLCSP70 (SOT2146-1)

WLCSP70, wafer level chip scale package, 70 terminals, 0.35 mm pitch, 3.64 mm x 3.16 mm x 0.49 mm body (backside coating included)

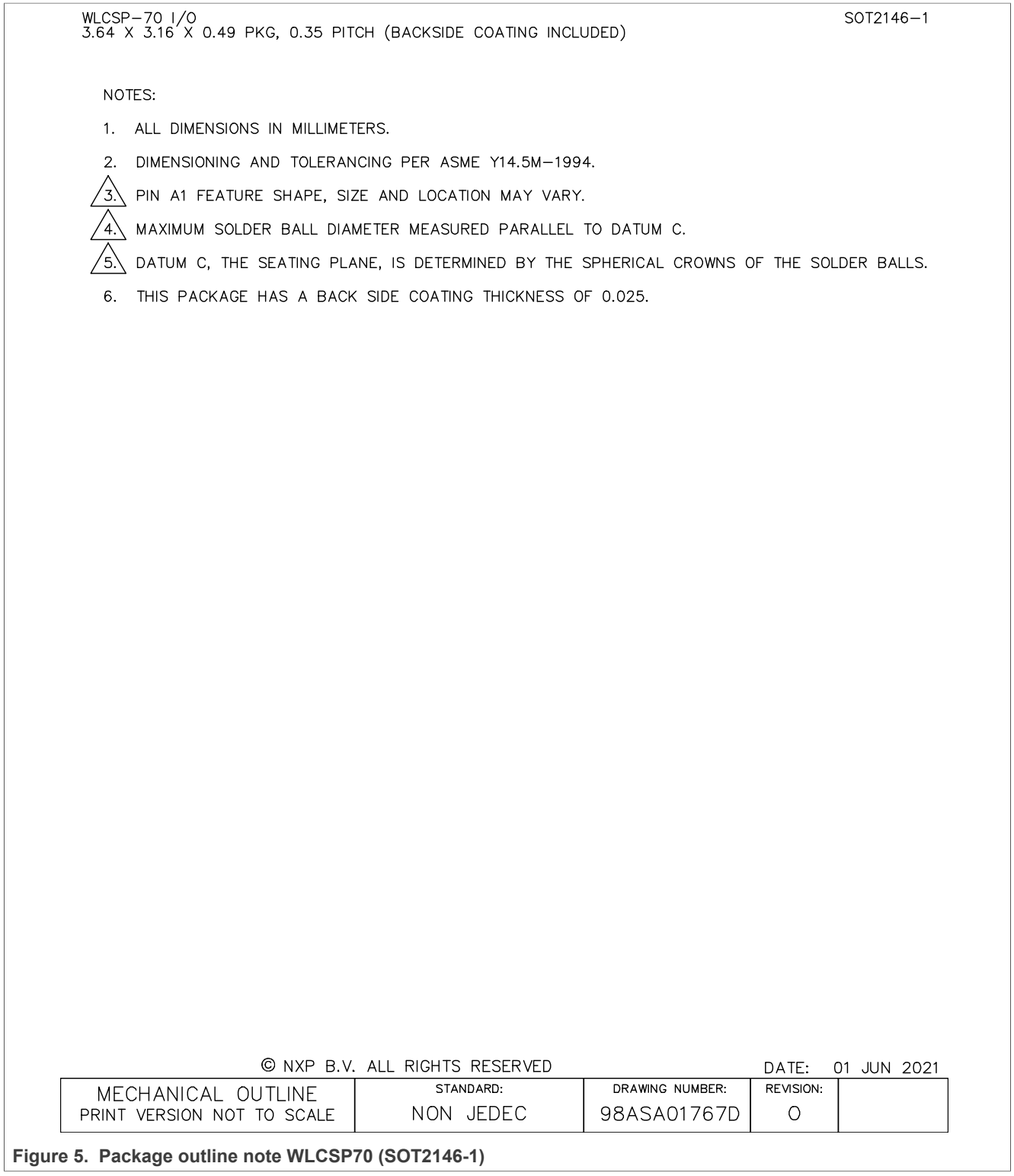

Figure 5. Package outline note WLCSP70 (SOT2146-1)

4 Legal information

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WLCSP70, wafer level chip scale package, 70 terminals, 0.35 mm pitch, 3.64 mm x 3.16 mm x 0.49 mm body (backside coating included)

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